# ne<mark>x</mark>peria

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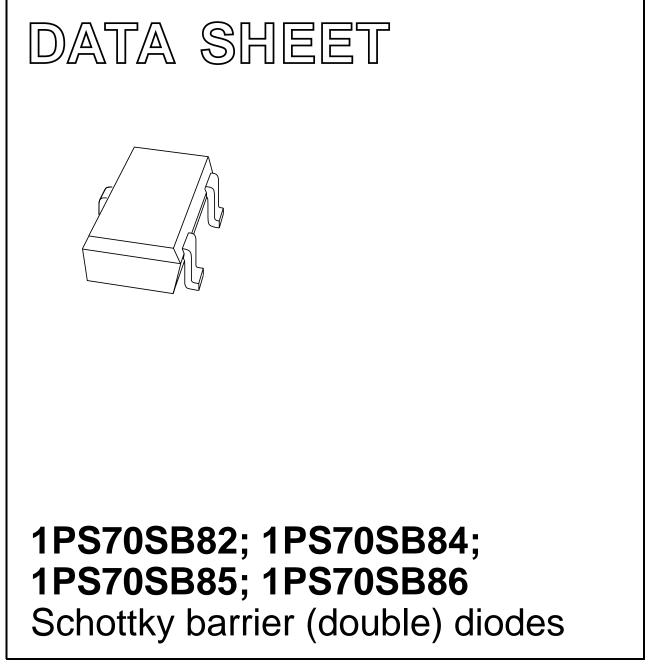
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Kind regards,

Team Nexperia

## DISCRETE SEMICONDUCTORS



Product data sheet

2001 Jan 18



## 1PS70SB82; 1PS70SB84; 1PS70SB85; 1PS70SB86

## FEATURES

- Low forward voltage
- Very small SMD plastic package
- Low diode capacitance.

## APPLICATIONS

- UHF mixers
- Sampling circuits
- Modulators
- Phase detectors.

## DESCRIPTION

Planar Schottky barrier diodes encapsulated in a SOT323 (SC-70) very small plastic SMD package. Single diodes and double diodes with different pinning are available. ESD sensitive device, observe handling precautions.

### MARKING

TYPE NUMBER	MARKING CODE
1PS70SB82	88
1PS70SB84	87
1PS70SB85	85
1PS70SB86	86

#### PINNING

PIN	SYMBOL	
1PS70SB82		
1	а	
2	n.c.	
3	k	
1PS70SB84		
1	a <sub>1</sub>	
2	k <sub>2</sub>	
3	$k_1$ and $a_2$	
1PS70SB85	5	
1	a <sub>1</sub>	
2	a <sub>2</sub>	
3	$k_1$ and $k_2$	
1PS70SB86		
1	k <sub>1</sub>	
2	k <sub>2</sub>	
3	$a_1$ and $a_2$	

**□** 3

Simplified outline

pin configuration.

(SOT323; SC-70) and

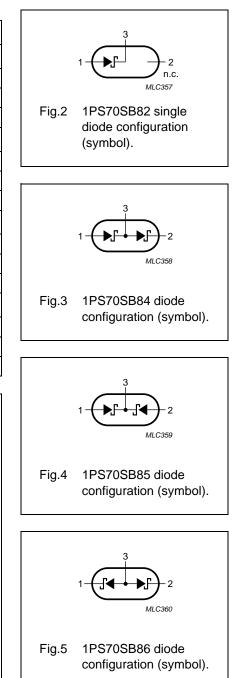
2

MBC870

⊢ı

Top view

Fig.1



## 1PS70SB82; 1PS70SB84; 1PS70SB85; 1PS70SB86

## LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER		MAX.	UNIT
Per diode	Per diode			
V <sub>R</sub>	continuous reverse voltage	_	15	V
I <sub>F</sub>	continuous forward current		30	mA
T <sub>stg</sub>	storage temperature		+150	°C
Tj	junction temperature		125	°C

## THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT	
R <sub>th j-a</sub>	thermal resistance from junction to ambient	note 1	625	K/W	

#### Note

1. Refer to (SOT323; SC-70) standard mounting conditions.

## **ELECTRICAL CHARACTERISTICS**

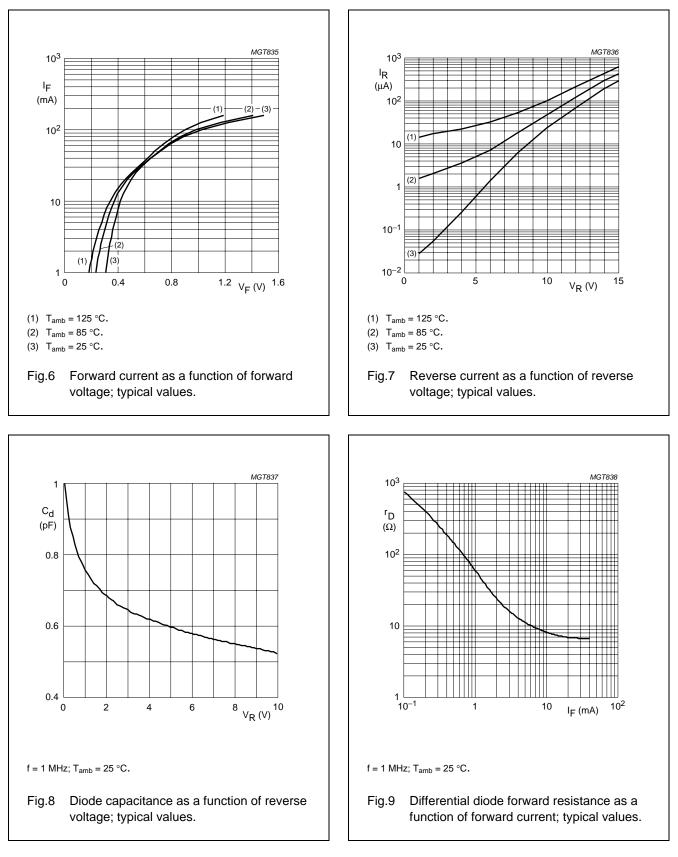
 $T_{amb}$  = 25 °C; unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	TYP.	MAX.	UNIT
Per diode					
V <sub>F</sub>	forward voltage	see Fig.6			
		I <sub>F</sub> = 1 mA	-	340	mV
		I <sub>F</sub> = 30 mA	_	700	mV
r <sub>D</sub>	differential diode forward resistance	$f = 1 \text{ MHz}; I_F = 5 \text{ mA}; \text{ see Fig.9}$	12	-	Ω
I <sub>R</sub>	continuous reverse current	$V_R = 1$ V; note 1; see Fig.7	_	0.2	μA
C <sub>d</sub>	diode capacitance	$V_R = 0$ ; f = 1 MHz; see Fig.8	1	_	pF

#### Note

1. Pulsed test:  $t_p = 300 \ \mu s$ ;  $\delta = 0.02$ .

## 1PS70SB82; 1PS70SB84; 1PS70SB85; 1PS70SB86



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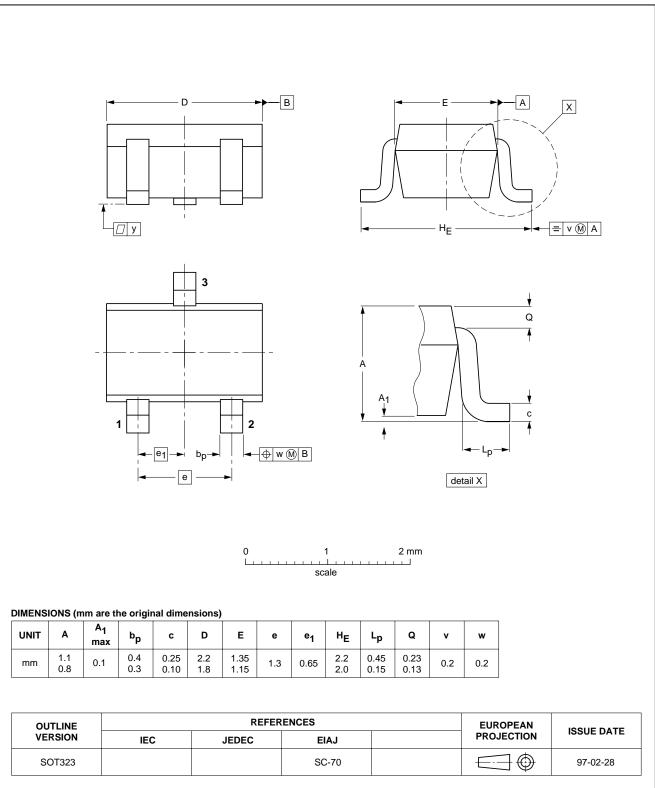
1PS70SB82; 1PS70SB84;

1PS70SB85; 1PS70SB86

## Schottky barrier (double) diodes

## PACKAGE OUTLINE

## Plastic surface mounted package; 3 leads



2001 Jan 18

Downloaded from Arrow.com.

#### SOT323

## 1PS70SB82; 1PS70SB84; 1PS70SB85; 1PS70SB86

## DATA SHEET STATUS

DOCUMENT STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)</sup>	DEFINITION
Objective data sheet	Development	This document contains data from the objective specification for product development.
Preliminary data sheet	Qualification	This document contains data from the preliminary specification.
Product data sheet	Production	This document contains the product specification.

#### Notes

- 1. Please consult the most recently issued document before initiating or completing a design.
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## **NXP Semiconductors**

### **Customer notification**

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#### **Contact information**

For additional information please visit: http://www.nxp.com For sales offices addresses send e-mail to: salesaddresses@nxp.com

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Printed in The Netherlands

613514/01/pp7

Date of release: 2001 Jan 18

Document order number: 9397 750 07669

